2SB0928, 2SB0928A (2SB928, 2SB928A)

Silicon PNP epitaxial planar type

For power amplification

For TV vartical deflection output

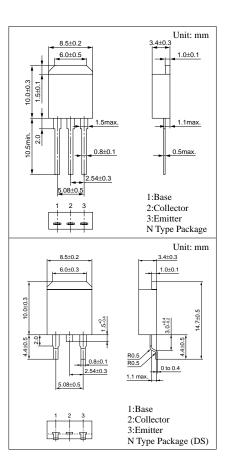
Complementary to 2SD1250 and 2SD1250A

Features

- High collector to emitter V_{CEO}
- High collector power dissipation P_C
- N type package enabling direct soldering of the radiating fin to the printed circuit board, etc. of small electronic equipment.

Absolute Maximum Ratings $(T_C=25^{\circ}C)$

Parameter		Symbol	Ratings	Unit	
Collector to base voltage		V_{CBO}	-200	V	
Collector to	2SB0928	**	-150	***	
emitter voltage	2SB0928A	V_{CEO}	-180	V	
Emitter to base voltage		V_{EBO}	-6	V	
Peak collector current		I _{CP}	-3	A	
Collector current		I_C	-2	A	
Collector power	T _C =25°C	D	30	***	
dissipation	Ta=25°C	P_{C}	1.3	W	
Junction temperature		T _j	150	°C	
Storage temperature		T_{stg}	-55 to +150	°C	



Electrical Characteristics (T_C=25°C)

Parameter		Symbol	Conditions	min	typ	max	Unit
Collector cutoff current		I_{CBO}	$V_{CB} = -200V, I_E = 0$			-50	μΑ
Emitter cutoff current		I _{EBO}	$V_{EB} = -4V, I_C = 0$			-50	μΑ
Collector to base voltage		V _{CBO}	$I_{\rm C} = -500 \mu A, I_{\rm E} = 0$	-200			V
Collector to emitter	2SB0928	V _{CEO}	$I_{\rm C} = -5 {\rm mA}, I_{\rm B} = 0$	-150			- V
voltage	2SB0928A			-180			
Emitter to base voltage		V _{EBO}	$I_{\rm E} = -500 \mu A, I_{\rm C} = 0$	-6			V
Forward current transfer ratio		h _{FE1} *	$V_{CE} = -10V, I_{C} = -150mA$	60		240	
		h _{FE2}	$V_{CE} = -10V, I_{C} = -400mA$	50			
Base to emitter voltage		V _{BE}	$V_{CE} = -10V, I_{C} = -400mA$			-1	V
Collector to emitter saturation voltage		V _{CE(sat)}	$I_C = -500 \text{mA}, I_B = -50 \text{mA}$			-1	V
Transition frequency		f_T	$V_{CE} = -10V, I_{C} = -0.5A, f = 10MHz$		30		MHz

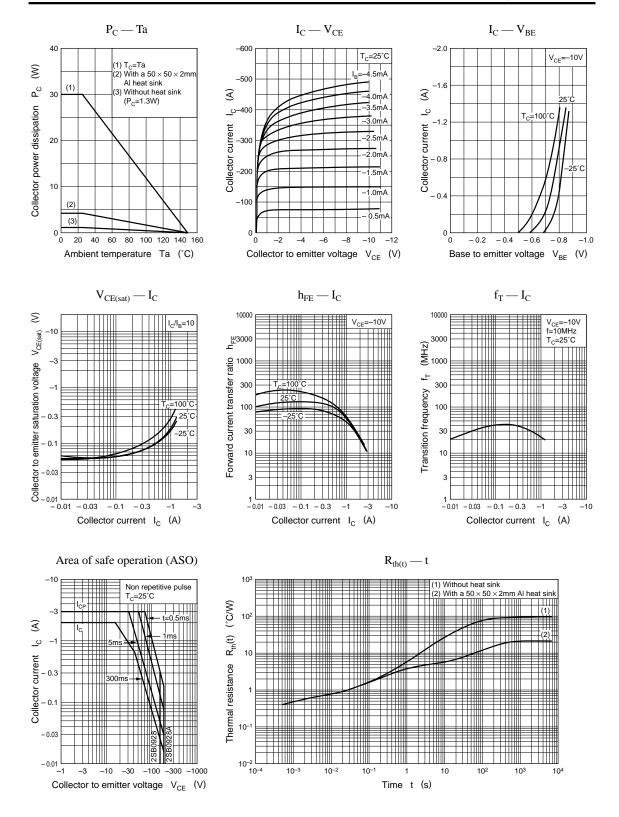
*h_{FE1} Rank classification

Rank	Q	P
h _{FE1}	60 to 140	100 to 240

Note) The part numbers in the parenthesis show conventional part number.

Note: Ordering can be made by the common rank (PQ rank $h_{FE1} = 60$ to 240) in the rank classification.

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